



# Session 4: Thermography

**Chairman Vincent Pouget, IMS Bordeaux**

<p>8:15-8:35</p>	<p>Application of Thermography: some examples (Stephane Bianic, STNwireless, Jean Roux, Hamamatsu)</p>
<p>8:35-9:05</p>	<p>Application of Lock-in Thermography for Defect Localisation at Opened and Fully Packaged Single- and Multi-chip Devices (Christian Schmidt, Christian Große, Frank Altmann Fraunhofer Institute for Mechanics of Materials, Halle, Germany &amp; Dr. Otwin Breitenstein Max Planck Institute of Microstructure Physics, Halle, Germany)</p>
<p>9:05-9:25</p>	<p>Application of transient interferometric mapping (TIM) technique for analysis of ns-time scale thermal and carrier dynamics in ESD protection devices (D. Pogany, S. Bychikhin, M. Heer, W. Mamanee, V.Dubec, E. Gornik, Institute for Solid State Electronics, Vienna University of Technology, D. Johnsson, K. Domanski, K. Esmark, W. Stadler, H. Gossner, M. Stecher, Infineon Technologies)</p>
<p>9:25-9:45</p>	<p>High Resolution Raman Temperature Measurements (Aaron Falk, QFI, USA)</p>
<p>9:45-10:05</p>	<p>Questions and answers (Christof Brillert, INFINEON Munich)</p>